

Contact: Andrea Roberts, A•R Marketing, Inc.
(858) 451-8666; andrea@armarketinginc.com

FOR IMMEDIATE RELEASE
Visit StratEdge at MTT-S Booth 2039

Photo available at <https://www.stratedge.com/G1010M-2.jpg>

StratEdge Unveils Series of Small Outline Thermally Enhanced Packages for Power Semiconductors

San Diego, Calif – April 16, 2008 – StratEdge, leader in the design and production of semiconductor packages for microwave, millimeter wave, and high speed digital devices, announces the introduction of a new family of small outline thermally enhanced molded ceramic packages for power semiconductors. The new line of packages can be used for silicon, silicon carbide, gallium nitride, and other compound semiconductors in power integrated circuit applications. Specific devices include amplifiers, discrete transistors, and diodes where greater than 0.5 Watt power is consumed.

These thermally enhanced packages are designed for reliability and to mitigate the inherent stresses of brazing dissimilar materials together. All materials used in the packages have matched coefficients of expansion. They are assembled using a glass-to-metal seal process combined with gold germanium brazing, resulting in a rugged and reliable package. The packages can handle temperatures up to 360 degrees Celsius. A hermetic seal provides enhanced reliability for the device and offers protection from harsh environmental conditions, meeting military standard requirements. Packages in this series are sealed with metal or ceramic lids that have gold-tin solder preforms.

These packages incorporate copper composite bases or copper inserts for enhanced thermal dissipation. Devices are mounted directly to the metal bases thus providing excellent electric ground to the backside of the chip. They provide superior electrical performance for frequencies up to at least 6 GHz. For controlled impedance devices, transition designs with higher frequency performance can be utilized.

Packages are available in various shapes, sizes, and lead counts. All can be provided with gull wing-shaped leads for surface mounting. A popular package is the two lead G1010M-2C

supplied with copper insert. The G1010M-2C has a 0.100 inch square (2.5mm square) outline with a 0.030 inch (0.75mm) by 0.055 inch (1.4mm) die attach area. Pricing at 10,000 units is about \$6.26 each. Pricing may vary due to order configuration, the price of gold, and shipping destination.

“These new packages, combined with our Power Package Series with thermally conductive beryllium oxide (BeO) ceramic, give our customers a variety of packages to choose from to package their high power devices,” said Timothy Going, president and CEO of StratEdge.

StratEdge’s new thermal power package can be seen at the MTT-S Show in Atlanta, Georgia from June 17-19 at booth 2039.

About StratEdge

StratEdge, founded in 1992, designs, manufactures, and provides test and assembly services for a complete line of high performance semiconductor packages operating from DC to 50+ GHz for the high speed digital (OC-48, OC-192, OC-768), mixed signal, broadband wireless, satellite, point-to-point/multipoint, VSAT, and test and measurement industries, as well as aerospace stripline filters. StratEdge offers ceramic, low cost molded ceramic and metal packages. All packages are lead-free and most meet RoHS and WEEE standards. For more information contact StratEdge at 866-424-4962, email: info@stratedge.com, or visit our website at www.stratedge.com.

#####

StratEdge
Casey Krawiec
6335 Ferris Square, Suite C
San Diego, CA 92121
Phone: 866-424-4962 or 858-569-5000
E-mail: c.krawiec@stratedge.com

A•R Marketing, Inc.
Andrea Roberts
PO Box 501528
San Diego, CA 92150
Phone: 858-451-8666
E-mail: andrea@armarketinginc.com